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- (54) Title:** METHOD OF COMMUNICATION BETWEEN FUNCTIONAL BLOCKS IN A SYSTEM-ON-CHIP AND SYSTEM-ON-CHIP THEREOF

- (57) Abstract:** There is provided a method of communication between functional blocks in a system-on-chip. The method includes: exchanging a respective public key between a first functional block and a second functional block in the system-on-chip (SoC) for a communication therebetween, the first functional block being a transmitter of the communication and the second functional block being a receiver of the communication; generating, at the first functional block, a first code based on the public key of the second functional block; generating, at the second functional block, a second code based on the public key of the first functional block; obfuscating, at the first functional block, an address associated with the communication based on the first code to produce an obfuscated address; transmitting, at the first functional block, the obfuscated address to the second functional block via an interconnect communication infrastructure in the system-on-chip; receiving, at the second functional block, the obfuscated address from the first functional block via the interconnect communication infrastructure; and deobfuscating, at the second functional block, the obfuscated address received based on the second code to produce a deobfuscated address associated with the communication. There is also provided a corresponding system-on-chip.

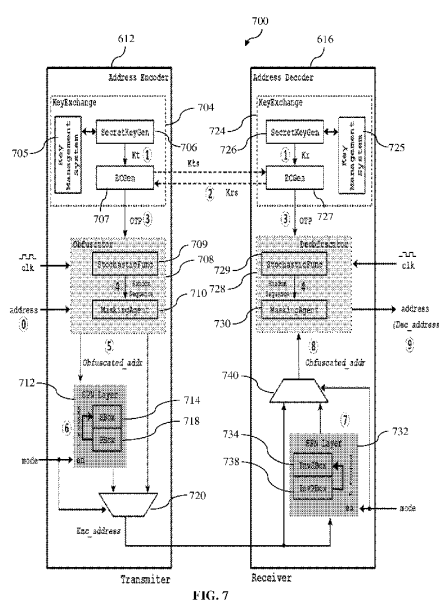


FIG. 7

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